

ABSTRACT

A computerized system and method for customizing bond programs in order to compensate first for variabilities in an integrated circuit (IC) "slave" bonder, and second to any irregularities in a "slave" circuit positioned on the slave bonder for attaching connecting bonds onto the IC bond pads. According to the invention, a "master" segmentator groups the bond pads of a "master" circuit on a master bonder into segments and stores the reference data related to these segments in a master file. Next, a slave regenerator, coupled to the master file, regenerates the master reference data so that variable characteristics of the slave bonder are defined and adaptively compensated. Finally, a slave corrector, coupled to the slave regenerator, corrects the bond program for the slave circuit on the adaptively compensated slave bonder. The slave bonder attaches the connecting bonds based on the computed correct bond locations.